

## IN THE CLAIMS

Claim 1 (currently amended). An adhesive sheet of an adhesive system composed of a thermoplastic and optionally one or more resins, wherein having

- a) ~~the adhesive system has~~ a softening temperature of greater than 65°C and less than 125°C,
- b) a melt flow index (ISO 1133) of greater than 3 and less than 100 cm<sup>3</sup>/10 minutes,
- c) a storage modulus G' at 23°C, as measured by test method A, of greater than 10<sup>7</sup> Pas,
- d) a loss modulus G'' at 23°C, as measured by test method A, of greater than 10<sup>6</sup> Pas,
- e) and a crossover, as measured by test method A, of less than 125°C.

Claim 2 (currently amended). The adhesive sheet of claim 1, ~~characterized in that~~ wherein the layer thickness is between 10 and 100 µm, ~~with particular preference between 30 and 80 µm.~~

Claim 3 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that thermoplastics used are with particular preference~~ claim 1, wherein said thermoplastic is selected from the group consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 4 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that reactive resin used comprises~~ claim 1, wherein said resins are reactive resins comprising one or more members of the group consisting of epoxy resins, ~~and/or~~ phenolic resins ~~and/or~~ novolak resins.

Claim 5 (currently amended). ~~The use of an adhesive sheet of any one of the above claims~~ A method for bonding chip modules in card bodies which comprises bonding said chip modules in said card bodies with the adhesive sheet of claim 1.

Claim 6 (currently amended). ~~The use of an adhesive sheet of any one of the above claims for bonding~~ method of claim 5, wherein said chip modules are polyimide-, polyester or epoxy-based chip modules and ~~on~~ said card bodies are PVC, ABS, PET, PC, PP or PE card bodies.

Claim 7 (currently amended). A method for producing a heat-activable adhesive tape, ~~characterized in that an adhesive sheet of claims 1 to 4 is coated~~ which comprises coating an adhesive system composed of a thermoplastic and optionally one or more resins, having

- a) a softening temperature of greater than 65°C and less than 125°C,
- b) a melt flow index (ISO 1133) of greater than 3 and less than 100 cm<sup>3</sup>/10 minutes,
- f) a storage modulus G' at 23°C, as measured by test method A, of greater than 10<sup>7</sup> Pas,
- g) a loss modulus G'' at 23°C, as measured by test method A, of greater than 10<sup>6</sup> Pas,
- h) and a crossover, as measured by test method A, of less than 125°C

onto a release paper or a release film.

Claim 8 (new). The adhesive sheet of claim 2, wherein said layer thickness is between 30 and 80 µm.